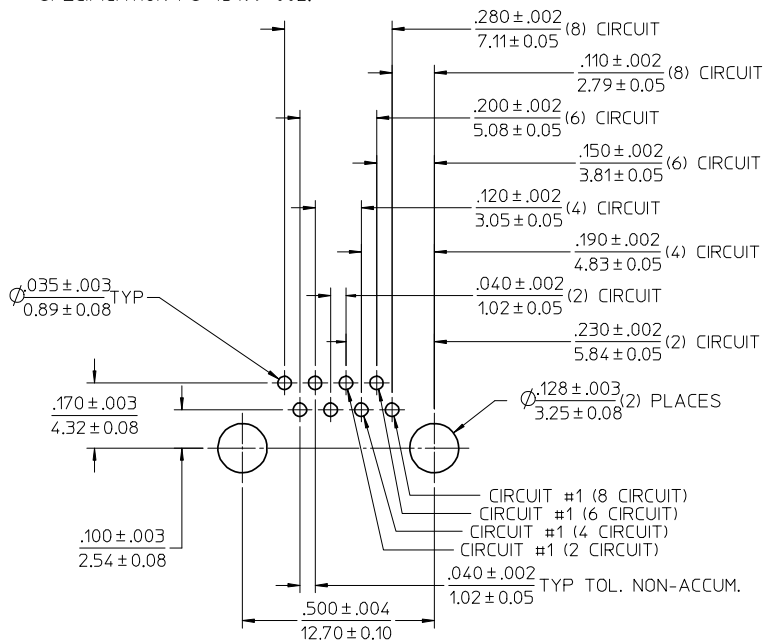
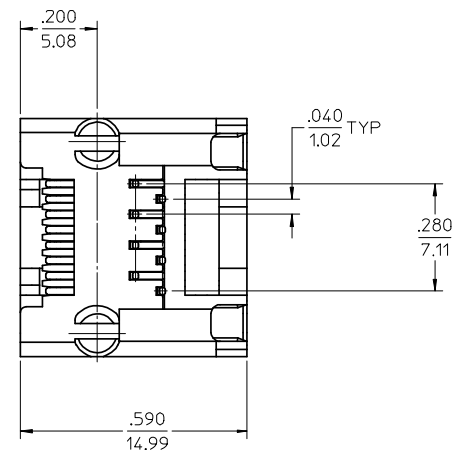
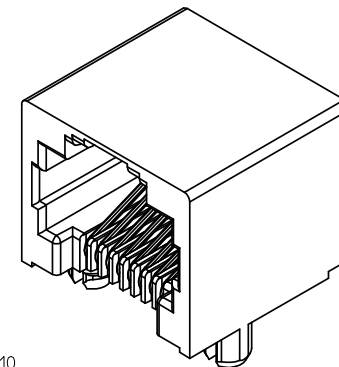
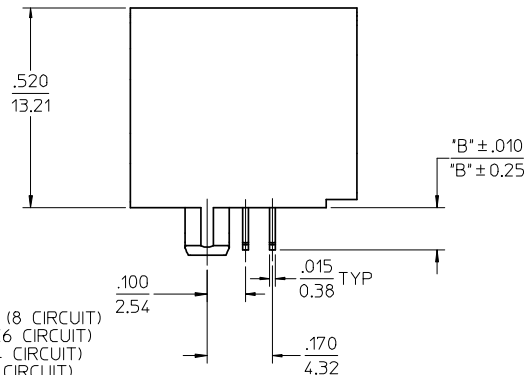
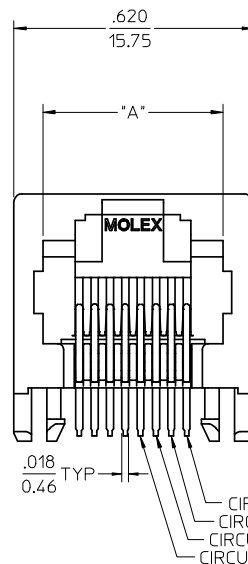


NOTES:

- 1) MATERIAL:  
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: SEE CHART  
TERMINALS: PHOSPHOR BRONZE
- 2) FINISH:  
TERMINALS:  
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.  
\*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,  
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.  
\*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO  
RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE  
2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT  
WITH TIN-LEAD IN THE PC TAILS.
- 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
- 4) PACKAGING SPECIFICATION:  
CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX  
PACKAGING SPECIFICATION PK-43860-004.
- 5) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 6) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 7) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC  
SPECIFICATION PS-45499-002.



PC BOARD LAYOUT  
COMPONENT SIDE OF BOARD  
RECOMMENDED PCB THICKNESS .062±.005/1.57±0.13



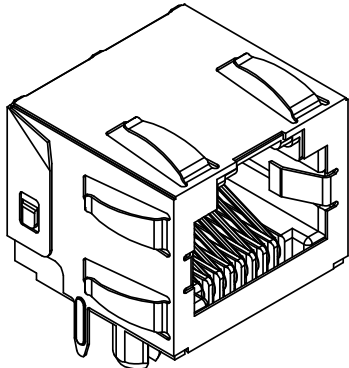
ASSEMBLY MAT. NUM.	CONNECTOR SIZE	DIM "A"	DIM "B"	CIRCUITS	HOUSING COLOR
43860-0001	8	.469/11.91	.110/2.79	8	BLACK
43860-2001	8	.469/11.91	.080/2.03	8	BLACK
43860-0002	6	.389/9.88	.110/2.79	6	BLACK
43860-0003	6	.389/9.88	.110/2.79	4	BLACK
43860-0019	8	.469/11.91	.110/2.79	4	BLACK
43860-0020	6	.389/9.88	.110/2.79	2	BLACK

ADD PART #, SHT 2 EC NO: UCP2008-3111 DRAWN: SCHMIDT 2008/06/20 CHKD: JEBEL 2008/06/27 APPR: FSMITH 2008/07/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0 ▽=0	mm INCH	IN/MM	4:1	INCH	

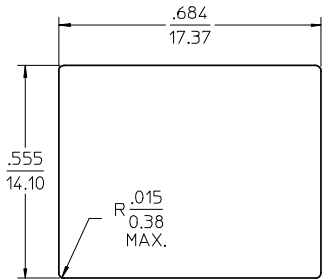
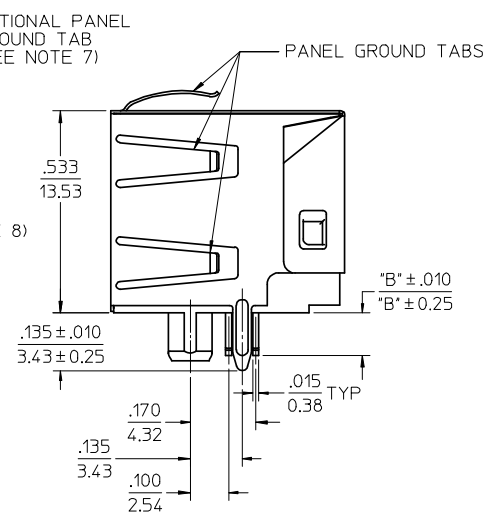
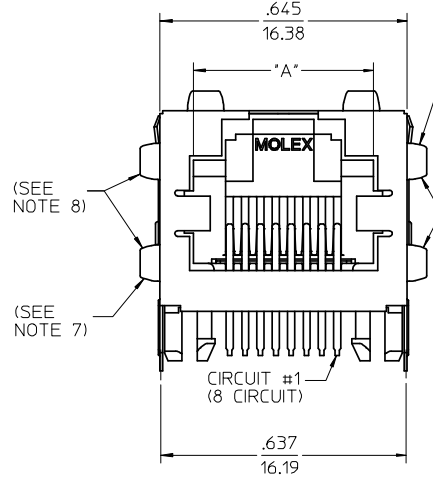
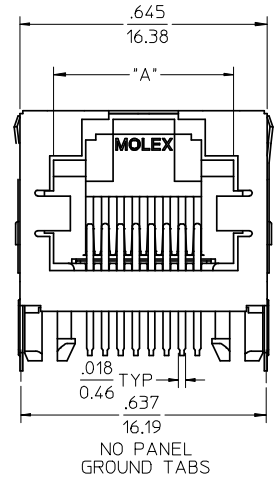
4 PLACES ± --- ± ---	3 PLACES ± --- ± .010	2 PLACES ± 0.25 ± ---	1 PLACE ± --- ± ---
ANGULAR ±1/2°			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			

DRAWN BY	DATE
TALEND	1997/02/13
CHECKED BY	DATE
ROBERTS	1997/03/03
APPROVED BY	DATE
FRY	1997/03/04
MATERIAL NO.	DOCUMENT NO.
SEE CHART	SD-43860-001
SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

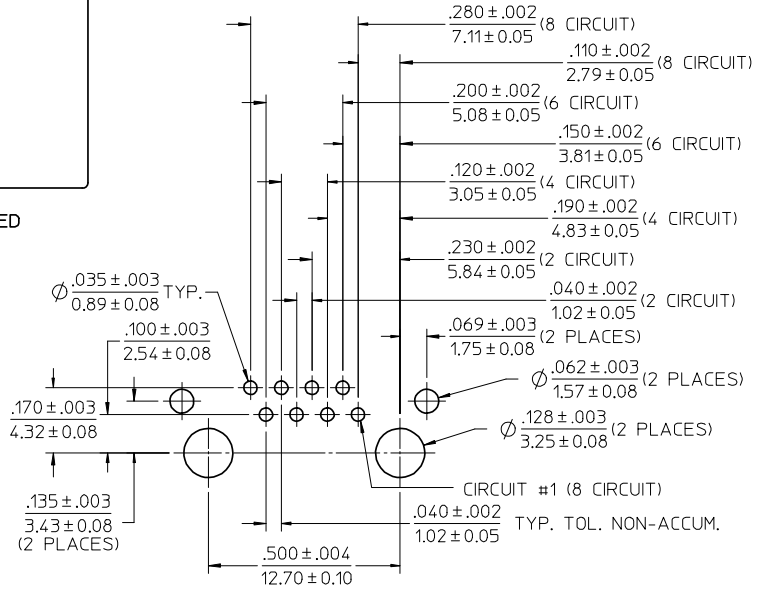
TITLE		INVERTED MODULAR JACK ASSEMBLY	
MOLEX		MOLEX INCORPORATED	
DOCUMENT NO.		SD-43860-001	
SHEET NO.		1 OF 5	



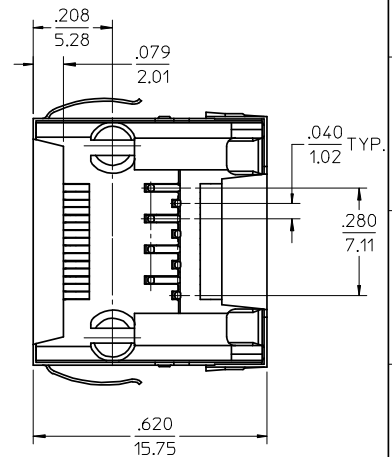
- NOTES:
- MATERIAL:  
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0,  
COLOR: BLACK  
TERMINALS: PHOSPHOR BRONZE  
SHIELD: BRASS
  - FINISH:  
TERMINALS:  
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES/  
1.27 MICROMETERS MIN.  
\*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES/  
2.54 MICROMETERS MIN.,  
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES/  
1.27 MICROMETERS MIN.  
SHIELD:  
\*100 MICROINCHES/2.54 MICROMETERS NICKEL OVER  
50 MICROINCHES/1.27 MICROMETERS COPPER  
UNDERPLATE, PCB GROUND TABS DIPPED IN TIN  
\*THE PRIMARY SHIPPING CARTON WILL BE LABELED  
"COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND  
ELV ANNEX II OF DIRECTIVE 2000/53/EC".  
CARTONS WITHOUT THIS LABEL MAY CONTAIN  
PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
  - PRODUCT SPECIFICATION: PS-43860-003.
  - PACKAGING SPECIFICATION:  
CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS  
PER MOLEX PACKAGING SPECIFICATION PK-43860-005.  
43860-5025 CONNECTOR ASSEMBLIES PACKAGED IN TAPE AND  
REEL PER MOLEX PACKAGING SPECIFICATION PK-70873-700\*
  - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
  - CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
  - AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS  
OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY  
MATERIAL NUMBER TABLE.
  - AVAILABLE WITH TOP PANEL GROUND TABS ONLY, PER THE  
ASSEMBLY MATERIAL NUMBER TABLE.
  - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC  
SPECIFICATION PS-45499-002.



RECOMMENDED  
PANEL  
OPENING

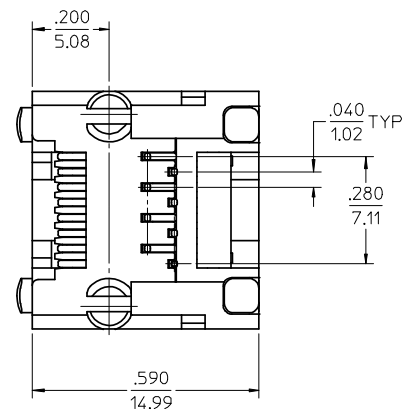
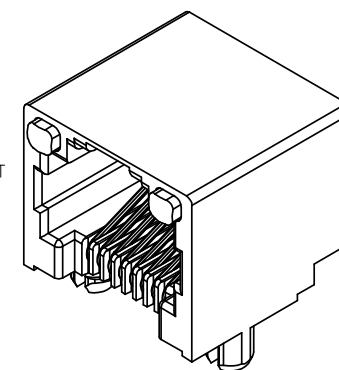
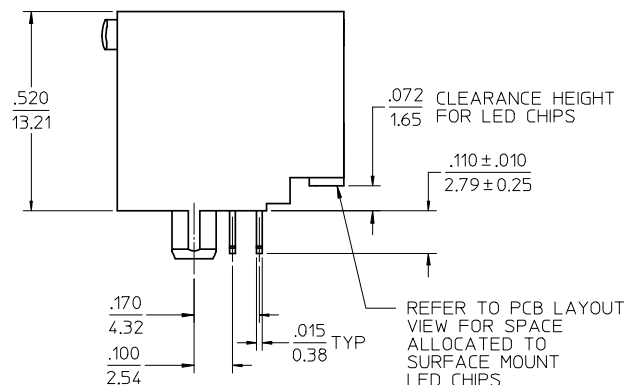
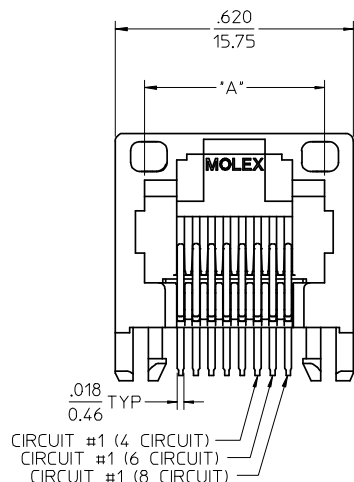


PC BOARD LAYOUT  
COMPONENT SIDE OF BOARD  
RECOMMENDED PCB THICKNESS .062 ± .005/1.57 ± 0.13



ASSEMBLY MAT. NUM.	CONNECTOR SIZE	DIM "A"	DIM "B"	CIRCUITS	PANEL GROUND TABS	PACKAGING OPTION
43860-0004	8	.469/11.91	.110/2.79	8	ALL	TRAY
43860-2004	8	.469/11.91	.080/2.03	8	ALL	TRAY
43860-0005	6	.389/9.88	.110/2.79	6	ALL	TRAY
43860-0006	6	.389/9.88	.110/2.79	4	ALL	TRAY
43860-0013	8	.469/11.91	.110/2.79	8	SEE NOTE #7	TRAY
43860-0014	6	.389/9.88	.110/2.79	6	SEE NOTE #7	TRAY
43860-0015	6	.389/9.88	.110/2.79	4	SEE NOTE #7	TRAY
43860-0024	6	.389/9.88	.110/2.79	2	ALL	TRAY
43860-0025	8	.469/11.91	.110/2.79	8	NONE	TRAY
43860-0026	6	.389/9.88	.110/2.79	6	NONE	TRAY
43860-0027	6	.389/9.88	.110/2.79	4	NONE	TRAY
43860-0031	8	.469/11.91	.110/2.79	8	SEE NOTE #8	TRAY
43860-5025	8	.469/11.91	.110/2.79	8	NONE	TAPE

ADD 43860-5025 EC NO: UCP2008-3111 DRAWN: SCHMIDT 2008/06/20 CHKD: JEBEL 2008/06/27 APPR: FSM/TH 2008/07/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
	▽=0	mm INCH	DRAWN BY TALEND DATE 1997/02/13	TITLE INVERTED MODULAR JACK ASSEMBLY		
	▽=0	4 PLACES ± --- ± ---	CHECKED BY ROBERTS DATE 1997/03/03	MOLEX MOLEX INCORPORATED		
		3 PLACES ± --- ± .010	APPROVED BY FRY DATE 1997/03/04	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-43860-001	SHEET NO. 2 OF 5
H6	ANGULAR ±1/2°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



NOTES:

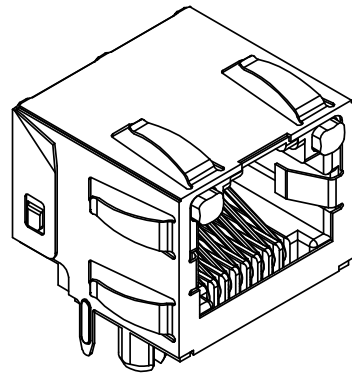
- 1) MATERIAL:  
 HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK  
 TERMINALS: PHOSPHOR BRONZE  
 LIGHT PIPES: POLYCARBONATE - WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)  
 POLYSULFONE - MAXIMUM REFLOW TEMPERATURE 400°F (205°C)
- 2) FINISH:  
 TERMINALS:  
 SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,  
 \*SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,  
 WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.  
 \*THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS.
- 3) PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
- 4) PACKAGING SPECIFICATION:  
 CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX PACKAGING SPECIFICATION PK-43860-004.
- 5) APPLICATION SPECIFICATION: AS-43860-001
- 6) ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
- 7) CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
- 8) REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
- 9) THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

ASSEMBLY MAT. NUM.	LIGHT PIPE MATERIAL	CONNECTOR SIZE	DIM "A"	CIRCUITS
43860-0007	POLYCARBONATE	8	.469/11.91	8
43860-0008	POLYCARBONATE	6	.389/9.88	6
43860-0009	POLYCARBONATE	6	.389/9.88	4
43860-0021	POLYSULFONE	8	.469/11.91	8
43860-0022	POLYSULFONE	6	.389/9.88	6
43860-0023	POLYSULFONE	6	.389/9.88	4

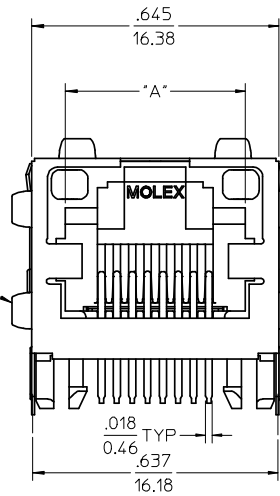
SEE SHEET 1 EC NO: UCP2008-3111 DRAWN: SCHMIDT CHKD: JEBEL APPR: FSMITH	2008/06/20 2008/06/27 2008/07/14	DESCRIPTION H6	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
			4 PLACES ± --- ± --- 3 PLACES ± --- ± .010 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1/2°	DRAWN BY TALEND DATE 1997/02/13	CHECKED BY ROBERTS DATE 1997/03/03	TITLE INVERTED MODULAR JACK ASSEMBLY		
			APPROVED BY FRY DATE 1997/03/04					
			MATERIAL NO. SEE CHART		DOCUMENT NO. SD-43860-001		SHEET NO. 3 OF 5	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

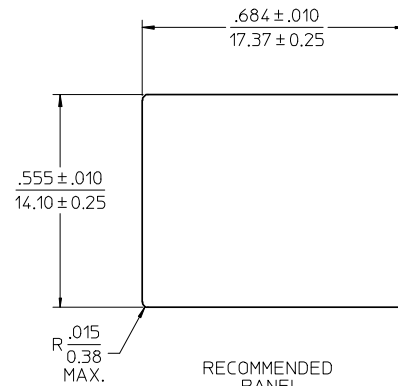
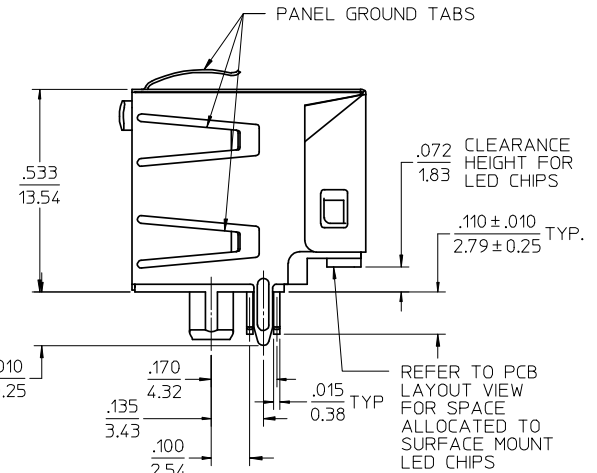
SIZE C THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



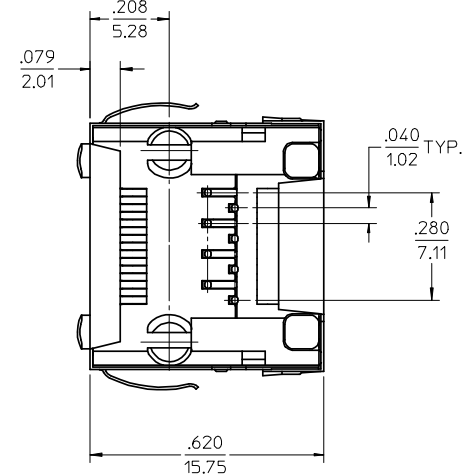
OPTIONAL PANEL GROUND TAB (SEE NOTE 8)



OPTIONAL PANEL GROUND TAB (SEE NOTE 8)



RECOMMENDED PANEL OPENING



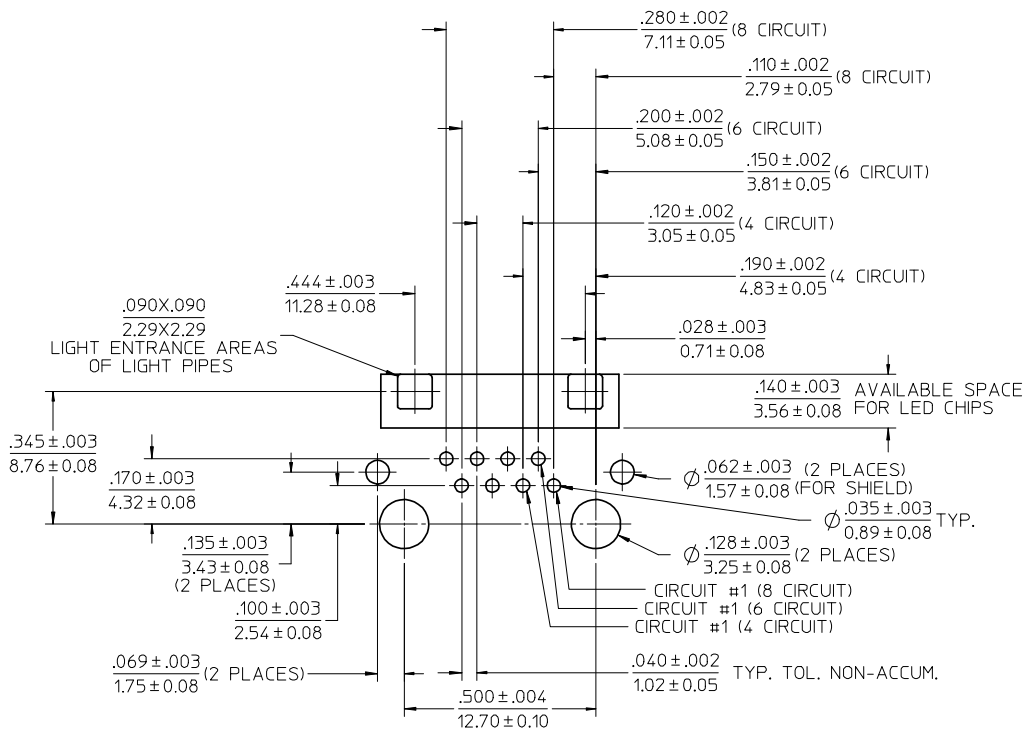
- NOTES:
- MATERIAL:
    - HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK
    - TERMINALS: PHOSPHOR BRONZE
    - SHIELD: BRASS
    - LIGHT PIPES:
      - POLYCARBONATE - WAVE OR HAND SOLDER ONLY (NOT DESIGNED FOR I/R REFLOW OR CONVECTION REFLOW SOLDER PROCESSES)
      - POLYSULFONE - MAXIMUM REFLOW TEMPERATURE 400° F (205° C)
  - FINISH:
    - TERMINALS:
      - SELECT GOLD IN CONTACT AREA: 50 MICROINCHES/1.27 MICROMETERS MIN.
      - SELECT TIN IN PC TAIL AREA: 100 MICROINCHES/2.54 MICROMETERS MIN.
      - WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES/1.27 MICROMETERS MIN.
    - SHIELD:
      - \*100 MICROINCHES/2.54 MICROMETERS OVER 50 MICROINCHES/1.27 MICROMETERS COPPER UNDERPLATE, PCB GROUND TABS DIPPED IN TIN
      - \*THE PRIMARY SHIPPING CARTON WILL BE LABELED 'COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC'. CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH TIN-LEAD IN THE PC TAILS AND/OR SHIELD.
  - PRODUCT SPECIFICATION AND PROCESSING PARAMETERS: PS-43860-003.
  - PACKAGING SPECIFICATION:
    - CONNECTOR ASSEMBLIES PACKAGED IN THERMOFORMED TRAYS PER MOLEX PACKAGING SPECIFICATION PK-43860-005.
  - APPLICATION SPECIFICATION: AS-43860-001
  - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
  - CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
  - AVAILABLE WITH THE (2) SPECIFIED PANEL GROUND TABS OMITTED FOR SIDE TO SIDE STACKABILITY, PER THE ASSEMBLY MATERIAL NUMBER TABLE.
  - REFER TO SHEET (5) OF (5) FOR RECOMMENDED PCB LAYOUT.
  - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPECIFICATION PS-45499-002.

ASSEMBLY MAT. NUM.	LIGHT PIPE MATERIAL	CONNECTOR SIZE	DIM "A"	CIRCUITS	PANEL GROUND TABS
43860-0010	POLYCARBONATE	8	.469/11.91	8	ALL
43860-0011	POLYCARBONATE	6	.389/9.88	6	ALL
43860-0012	POLYCARBONATE	6	.389/9.88	4	ALL
43860-0016	POLYCARBONATE	8	.469/11.91	8	SEE NOTE #8
43860-0017	POLYCARBONATE	6	.389/9.88	6	SEE NOTE #8
43860-0018	POLYCARBONATE	6	.389/9.88	4	SEE NOTE #8
43860-1010	POLYSULFONE	8	.469/11.91	8	ALL
43860-1011	POLYSULFONE	6	.389/9.88	6	ALL
43860-1012	POLYSULFONE	6	.389/9.88	4	ALL
43860-1016	POLYSULFONE	8	.469/11.91	8	SEE NOTE #8
43860-1017	POLYSULFONE	6	.389/9.88	6	SEE NOTE #8
43860-1018	POLYSULFONE	6	.389/9.88	4	SEE NOTE #8

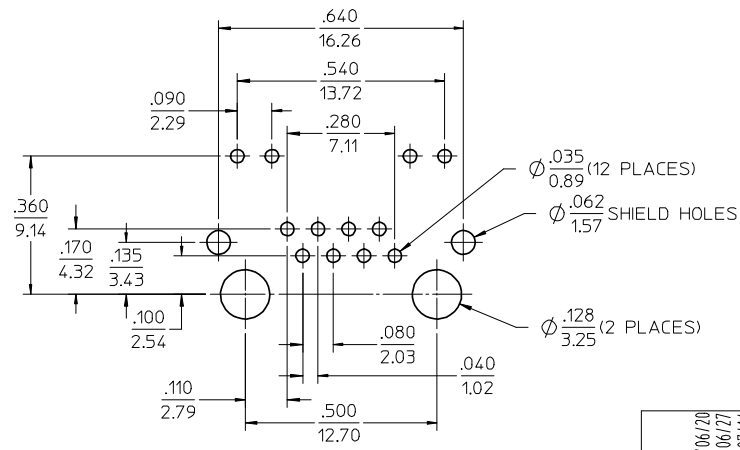
SEE SHEET 1 EC NO: UCP2008-3111 DRAWN: SCHMIDT 2008/06/20 CHKD: JEBEL 2008/06/27 APPR: FSM/TH 2008/07/14	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES ±</td> <td>---</td> <td>±---</td> </tr> <tr> <td>3 PLACES ±</td> <td>---</td> <td>±.010</td> </tr> <tr> <td>2 PLACES ±</td> <td>0.25</td> <td>±---</td> </tr> <tr> <td>1 PLACE ±</td> <td>---</td> <td>±---</td> </tr> </table>		mm	INCH	4 PLACES ±	---	±---	3 PLACES ±	---	±.010	2 PLACES ±	0.25	±---	1 PLACE ±	---	±---	DIMENSION STYLE IN/MM	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION
		mm	INCH																		
	4 PLACES ±	---	±---																		
	3 PLACES ±	---	±.010																		
2 PLACES ±	0.25	±---																			
1 PLACE ±	---	±---																			
		DRAWN BY TALEND	DATE 1997/02/13	TITLE <b>INVERTED MODULAR JACK ASSEMBLY</b>																	
		CHECKED BY ROBERTS	DATE 1997/03/03	MOLEX INCORPORATED																	
		APPROVED BY FRY	DATE 1997/03/04	MATERIAL NO. <b>SEE CHART</b>	DOCUMENT NO. <b>SD-43860-001</b>	SHEET NO. <b>4 OF 5</b>															

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

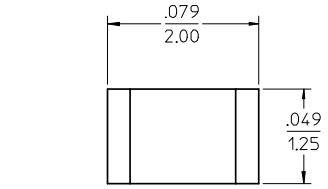
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



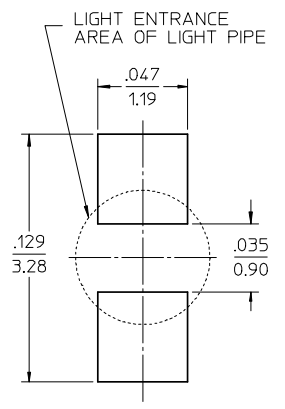
MOLEX RECOMMENDED PCB BOARD LAYOUT COMPONENT SIDE OF BOARD RECOMMENDED PCB THICKNESS .062±.005/1.57±0.13



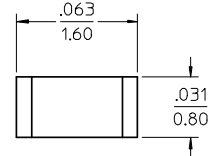
TYPICAL COMPETITION PCB LAYOUT WITH INTEGRAL LED'S (SHOWN FOR REFERENCE ONLY)



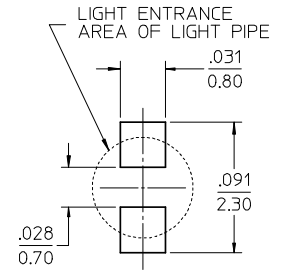
RECOMMENDED SMT 0805 LED DIMENSIONS SCALE 20:1 (SEE NOTE 1)



RECOMMENDED SMT 0805 LED SOLDER PATTERN SCALE 20:1 (SEE NOTE 1)



RECOMMENDED SMT 0603 LED DIMENSIONS SCALE 20:1 (SEE NOTE 1)



RECOMMENDED SMT 0603 LED SOLDER PATTERN SCALE 20:1 (SEE NOTE 1)

NOTES:  
1. FOR CROSS REFERENCE OF RECOMMENDED LED'S SEE MOLEX WEB SITE

SEE SHEET 1 EC NO: UCP2008-3111 DRAWN: SCHMIDT 2008/06/20 CHKD: BELLE 2008/06/27 APPR: FSMITH 2008/07/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	IN/MM	4:1	INCH	
	▽=0	± .25	DRAWN BY DATE	TITLE	INVERTED MODULAR JACK ASSEMBLY	
		ANGULAR ±1/2°	CHECKED BY DATE			

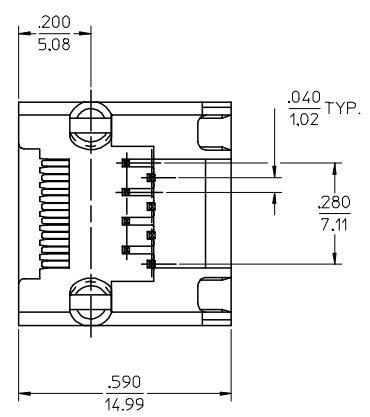
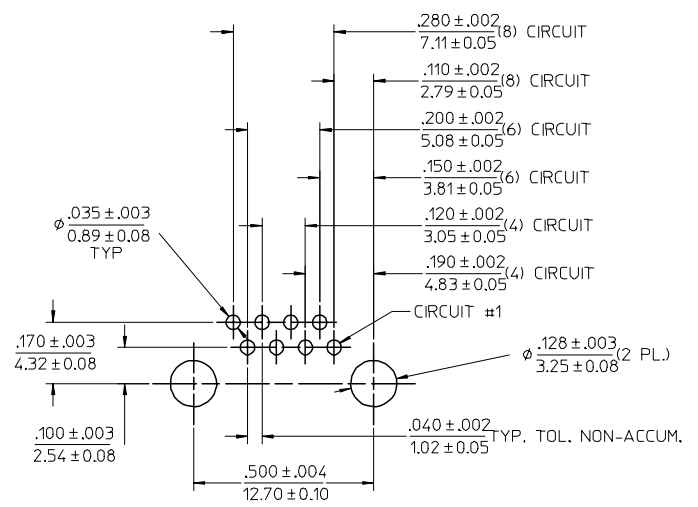
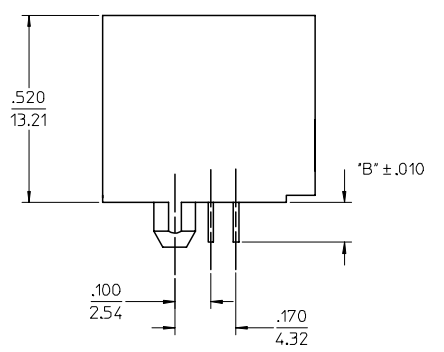
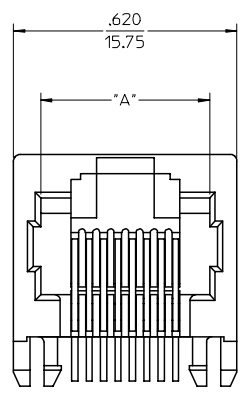
APPROVED BY DATE	DOCUMENT NO.	SHEET NO.
FRY 1997/03/04	SD-43860-001	5 OF 5
MATERIAL NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
SIZE	SEE CHART	

APPROVED BY DATE	DOCUMENT NO.	SHEET NO.
FRY 1997/03/04	SD-43860-001	5 OF 5
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FRY 1997/03/04	SD-43860-001	5 OF 5
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SIZE	SEE CHART	

MATERIAL NUMBER	CONNECTOR SIZE	DIM. "A"	DIM. "B"	CIRCUITS
43860-3001	8	.469/11.91	.110/2.79	8
43860-3003	6	.389/9.88	.110/2.79	4

- NOTES:
- MATERIAL:  
HOUSING: NYLON(PA), GLASS FILLED, UL94V-0, COLOR: BLACK  
TERMINALS: PHOSPHOR BRONZE, .015/(0.38) THICK
  - FINISH:  
TERMINALS:  
SELECT GOLD IN CONTACT AREA: 50 MICROINCHES (1.27 MICROMETERS) MIN.,  
SELECT TIN IN PC TAIL AREA: 100 MICROINCHES (2.54 MICROMETERS) MIN.,  
WITH OVERALL NICKEL UNDERPLATE: 50 MICROINCHES (1.27 MICROMETERS) MIN.
  - PRODUCT SPECIFICATION: PS-43860-003.
  - PACKAGING SPECIFICATION:  
CONNECTOR ASSEMBLIES PACKAGED IN EXTRUDED TUBES PER MOLEX  
PACKAGING SPECIFICATION PK-43860-004.
  - ALL UNTOLERANCED DIMENSIONS ARE SHOWN FOR REFERENCE ONLY.
  - CONFORMS TO FCC REGULATION PART 68.5 FOR MODULAR JACKS.
  - THE PRIMARY SHIPPING CARTON WILL BE LABELED, "COMPLIANT TO  
RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC."  
ASSEMBLIES WILL BE COMPLIANT TO THE RoHS AND ELV (LEAD-FREE)  
DIRECTIVES.



PC BOARD LAYOUT  
COMPONENT SIDE OF BOARD  
RECOMMENDED PCB THICKNESS .062 ± .005  
1.57 ± 0.13

ADD 43860-3001 EC NO: UCP2006-1667 DRAWN:LSCHMIDT 2006/02/14 CHKD:SSOUSEK 2006/02/14 APPR:FSMITH 2006/02/17	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	SCALE 4:1	DESIGN UNITS INCH	THIRD ANGLE PROJECTION	REVISE ON CAD ONLY
	DESCRIPTION	mm INCH	DIMENSION STYLE IN/MM	TITLE	INVERTED MODULAR JACK ASSEMBLY, LEAD-FREE	
A1	0	4 PLACES ± --- ± ---	DRAWN BY RHOLTS	DATE 2004/07/13	MOLEX INCORPORATED	
	0	3 PLACES ± --- ± .010	CHECKED BY LSCHMIDT	DATE 2004/07/13	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-43860-013
		2 PLACES ± 0.25 ± ---	APPROVED BY FSMITH	DATE 2004/07/13	SHEET NO. 1 OF 1	
		1 PLACE ± --- ± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		ANGULAR ±1/2°				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				